

NAND-Flash Code Information(1/3)

Last Updated : Dec. 2005

K **9** X X X X X X X X - X X X X X X X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18

1. Memory (K)

2. NAND Flash : 9

3. Small Classification

(SLC : Single Level Cell, MLC : Multi Level Cell,

SM : SmartMedia, S/B : Small Block)

1 : SLC 1 Chip XD Card

2 : SLC 2 Chip XD Card

4 : SLC 4 Chip XD Card

A : SLC + Muxed I/ F Chip

B : Muxed I/ F Chip

D : SLC Dual SM

E : SLC DUAL (S/ B)

F : SLC Normal

G : MLC Normal

H : MLC QDP

J : Non-Muxed One Nand

K : SLC Die Stack

L : MLC DDP

M : MLC DSP

N : SLC DSP

Q : 4CHIP SM

R : SLC 4DIE STACK (S/ B)

S : SLC Single SM

T : SLC SINGLE (S/ B)

U : 2 STACK MSP

V : 4 STACK MSP

W : SLC 4 Die Stack

4~5. Density

12 : 512M 16 : 16M 28 : 128M

32 : 32M 40 : 4M 56 : 256M

64 : 64M 80 : 8M 1G : 1G

2G : 2G 4G : 4G 8G : 8G

AG : 16G BG : 32G CG : 64G

DG : 128G 00 : NONE

6~7. Organization

00 : NONE

08 : x8

16 : x16

8. Vcc

A : 1.65V~3.6V

B : 2.7V (2.5V~2.9V)

C : 5.0V (4.5V~5.5V)

D : 2.65V (2.4V ~ 2.9V)

E : 2.3V~3.6V

R : 1.8V (1.65V~1.95V)

Q : 1.8V (1.7V ~ 1.95V)

T : 2.4V~3.0V

U : 2.7V~3.6V

V : 3.3V (3.0V~3.6V)

W : 2.7V~5.5V, 3.0V~5.5V

0 : NONE

9. Mode

0 : Normal

1 : Dual nCE & Dual R/ nB

4 : Quad nCE & Single R/ nB

5 : Quad nCE & Quad R/ nB

9 : 1st block OTP

A : Mask Option 1

L : Low grade

10. Generation

M : 1st Generation

A : 2nd Generation

B : 3rd Generation

C : 4th Generation

D : 5th Generation

Y : Partial NAND (2nd)

Z : Partial NAND (1st)

NAND-Flash Code Information(2/3)

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<u>K</u>	<u>9</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>-</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

11. "—"

12. Package

A : COB	B : TBGA
C : CHIP BIZ	D : 63-TBGA
E : TSOP1 (Lead-Free, 1217)	
F : WSOP (Lead-Free)	G : FBGA
H : TBGA (Lead-Free)	
I : ULGA (Lead-Free)	J : FBGA (Lead-Free)
K : TSOP1 (1217)	L : LGA
M : TLGA	N : TLGA2
P : TSOP1 (Lead-Free)	
Q : TSOP2 (Lead-Free)	
R : TSOP2-R	S : SMART MEDIA
T : TSOP2	U : COB (MMC)
V : WSOP	W : WAFER
Y : TSOP1	

13. Temp

C : Commercial	I : Industrial
S : SmartMedia	
B : SmartMedia BLUE	
0 : NONE (Containing Wafer, CHIP, BIZ, Exception handling code)	
3 : Wafer Level 3	

14. Bad Block

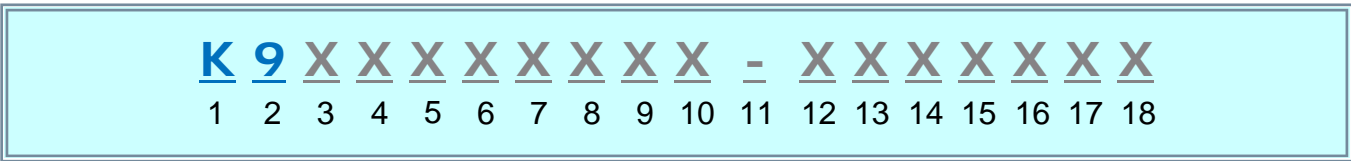
A : Apple Bad Block
 B : Include Bad Block
 D : Daisychain Sample
 K : Sandisk Bin
 L : 1~5 Bad Block
 N : ini. 0 blk, add. 10 blk
 S : All Good Block
 0 : NONE (Containing Wafer, CHIP, BIZ, Exception handling code)

15. NAND-Reserved

0 : Reserved

NAND-Flash Code Information(3/3)

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16. Packing Type

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Component (Mask ROM)	TRAY	Y
	AMMO PACKING	A
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"